



THERMOSET TOPCON

WORLD'S LEADING THERMOSET TECHNOLOGY CONFERENCE & EXPO

Madison, Wisconsin • May 12-13, 2026

Presented by SPE Thermoset Division

THE FUTURE OF THERMOSETS: AI AND EMERGING INDUSTRY INNOVATIONS

TUESDAY, MAY 12, 2026

ALL TIMES CT
(Central Time)

7:30-8:30

NETWORKING BREAKFAST *Sponsored by*



& EXHIBITS

8:30-8:40

WELCOME TO THE 2026 TOPCON SHOW: Sean Campbell, Chair TOPCON - LyondellBasell

DAY 1 AM MODERATOR: Len Nunnery, Board Member TOPCON - PLENCO

8:40-9:30

KEYNOTE

AI for Manufacturing

ADDRESS:

Matt Seitz, University of Wisconsin

9:30-10:00

MATERIAL:

Invest in Intelligence, Reap Rewards - An Abridged Case Study of the Materials Engineering Laboratory Expansion of Haysite Reinforced Plastics
Peter Fitzgerald, Haysite

10:00-10:30

MATERIAL:

Flame Retardant and Antimony Oxide Market Update
Glade Squires, OMYA

10:30-11:00

NETWORKING BREAK & EXHIBITS

11:00-11:30

MATERIAL:

The Izod Blind Spot: Experimental Proof that High-Speed Dynatup ASTM 3763 Test Differentiates Toughened SMCs where ASTM D256 Fails
Vinod Arora, Core Molding Technologies & Justin Moss, METTON

11:30-12:00

MATERIAL:

Sustainable Design of BMC Composites Using Circular, Recycled and Renewable Raw Materials
Hannah McClure & Dale Silvernell, IDI Composites International

12:00-1:00

NETWORKING LUNCHEON *Sponsored by*



& EXHIBITS

DAY 1 PM MODERATOR: Sean Campbell, Chair TOPCON - LyondellBasell

1:00-1:30

MOLDING:

A Look into the Operations of a Modern Mold Maker
Bob Boland, Versatile Mold and Design

1:30-2:00

TECHNICAL:

Towards Sustainable Resin "Kits" for Sheet Molding Compound
Jonathan McKay, ALTA Performance Materials

2:00-2:30

MATERIAL:

Properties and Composite Applications of Nanocalcite-Modified Epoxies: Lightweighting Opportunities
James Nelson, 3M Company

2:30-3:00

NETWORKING BREAK & EXHIBITS

3:00-3:30

TECHNICAL:

Digital Transformation in the Chemical Industry: From Strategy to Real-World Success
Kevin J. Meyer, Albert Invent

3:30-4:00

TECHNICAL:

Accelerated Fatigue Characterization of Composite Materials Through Entropy-Based Methodology
Mohammad Rouhi Moghanlou, Louisiana State University

4:00-4:15

DAY 1 CLOSING REMARKS Sean Campbell, Chair TOPCON - LyondellBasell

4:15-6:30

COCKTAIL RECEPTION *Sponsored by*



& EXHIBITS

6:30

CONFERENCE ADJOURNS FOR THE DAY

2026 AGENDA

2026 SPE THERMOSET TOPCON CONFERENCE



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WEDNESDAY, MAY 13, 2026

7:30-8:30

NETWORKING BREAKFAST & EXHIBITS

DAY 2 AM MODERATOR: Sean Campbell, Chair TOPCON - LyondellBasell

8:30-9:00

BUSINESS:

Global Composites Market Vision and Innovations in Sustainability

Paul Salach, Owens Corning

9:00-9:30

MATERIAL:

Development and Evaluation of Biochar-Filled Sheet Molding Compound (SMC) for Low-Shrink and Fire-Retardant Formulation

Eric Martin, Fraunhofer at Western University

9:30-10:00

MATERIAL:

Advanced Thermoset Composites: A Key Enabler in Next Generation Electronics

Jeff Gotro, InnoCentrix

10:00-10:30

NETWORKING BREAK & EXHIBITS

10:30-11:00

SUSTAINABILITY:

Preparing Your Lab for Industry 4.0: Automation, Clean Data, and AI in Material Development

Khaled Boqaileh, LabsCubed

11:00-11:30

MATERIAL:

AI Agents: Going Beyond Information Searching for Accelerating Composites Development

Kirsten V. Sommers, Independent Consultant

11:30-12:30

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& EXHIBITS

DAY 2 PM MODERATOR: Sean Campbell, Chair TOPCON - LyondellBasell

12:30-1:00

TECHNICAL:

Dielectric Cure Monitoring for Quality Testing of Sheet Molding Compound

Huan Lee, Lambient Technologies

1:00-1:30

TECHNICAL:

New Generation of Cobalt Free Accelerators for Thermoset Composites

Andy Palsule, Nouryon

1:30-2:00

TECHNICAL:

Experimental and Numerical Approach for Hybrid Fastening Systems with Dissimilar Substrates

Kunle Adeyemo, Michigan State University

2:00-2:30

CLOSING COMMENTS: TOPCON Board

2:30

CONFERENCE ADJOURNS FOR THE YEAR